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(12) United States Design Patent (10) Patent No.:

Pham et al.

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(54) EARPHONE HEADSET

(75) Inventors: Hoa Pham, Woodbury, MN (US);

Jason Lardy, Minneapolis, MN (US)

(73) Assignee: Telex Communications, Inc.,

Burnsville, MN (US)

(**) Term: 14 Years

(21) Appl. No.: 29/154,626

(22) Filed: Jan. 24, 2002

(52) U.S. Cl. D14/205

D14/142, 192, 223; 181/129, 130, 135; 379/430, 431; 381/151, 183, 187

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Primary Examiner—Paula A. Mortimer (74) Attorney, Agent, or Firm—Fredrikson & Byron, P.A.

(57) CLAIM

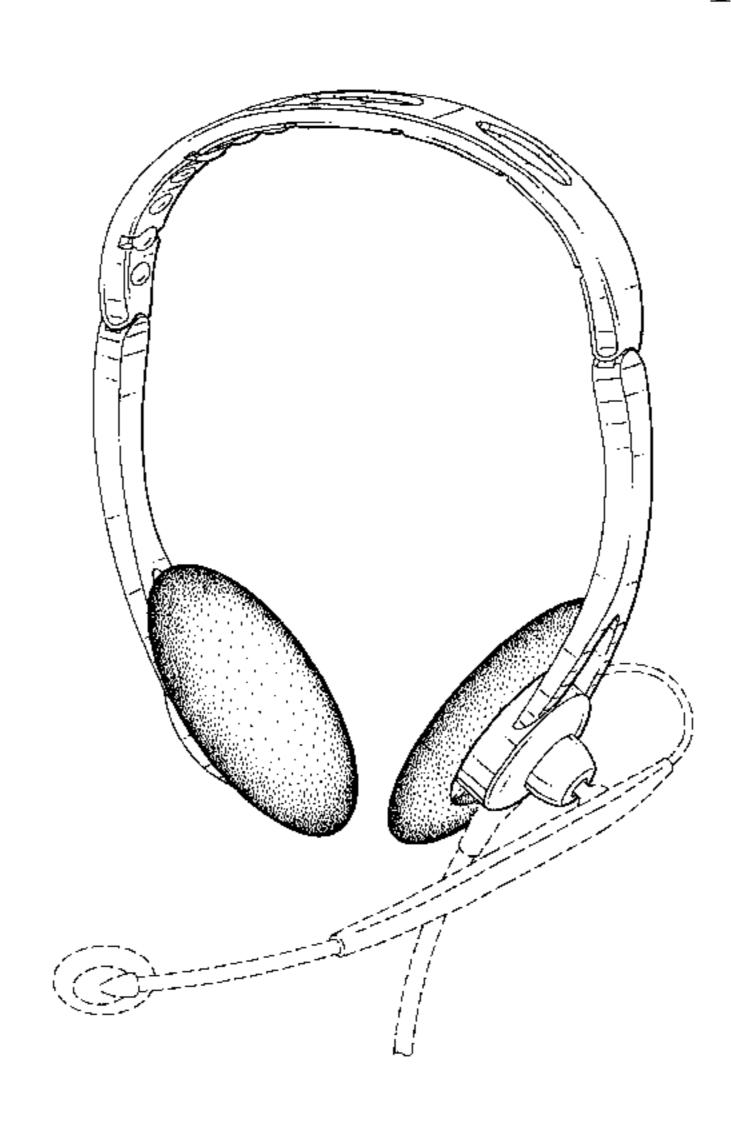
We claim the ornamental design for an earphone headset, as shown and described.

DESCRIPTION

- FIG. 1 is a perspective view of an earphone headset of the design as seen from the front and one side with the boom and the connection wiring shown in dotted lines that form no part of the claimed invention;
- FIG. 2 is a front elevation view thereof with the boom and connection wiring shown in dotted lines that form no part of the claimed invention;

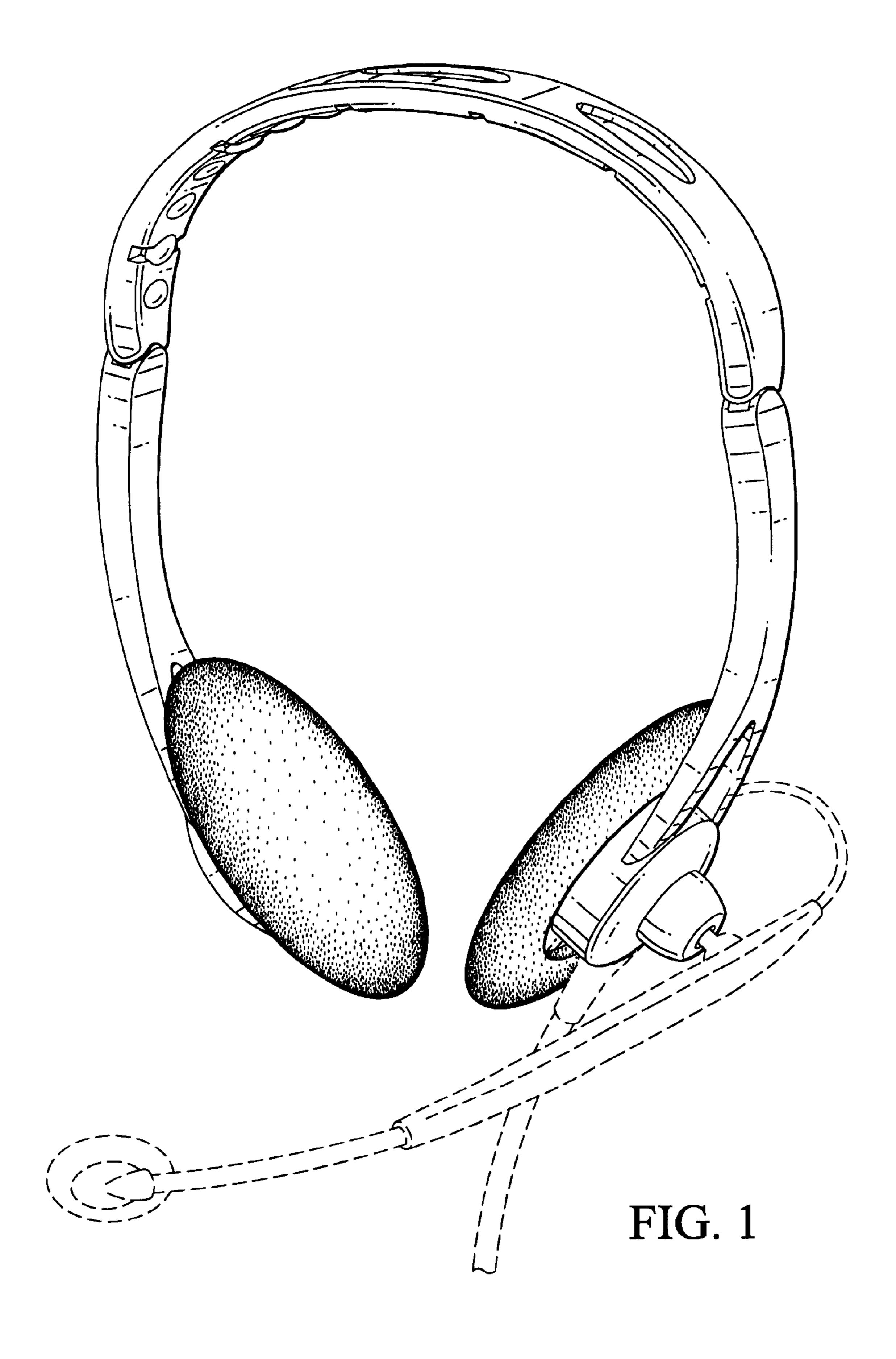
- FIG. 3 is a rear elevation view thereof with the boom and connection wiring shown in dotted lines that form no part of the claimed invention;
- FIG. 4 is a side elevation view as seen from left to right of the view shown in FIG. 2 with the boom and connection wiring shown in dotted lines that form no part of the claimed invention;
- FIG. 5 is a side elevation view as seen from right to left of the view shown in FIG. 2 with the boom and connection wiring shown in dotted lines that form no part of the claimed invention;
- FIG. 6 is a top plan view thereof with the boom and connection wiring shown in dotted lines that form no part of the claimed invention;
- FIG. 7 is a bottom plan view thereof with the boom and connection wiring shown in dotted lines that form no part of the claimed invention;
- FIG. 8 is a perspective view of a modified embodiment of the earphone headset of the design as seen from the front and one side with boom and the connection wiring shown in dotted lines that form no part of the claimed invention;
- FIG. 9 is a front elevation view thereof with the boom and connection wiring shown in dotted lines that form no part of the claimed invention;
- FIG. 10 is a rear elevation view thereof with the boom and connection wiring shown in dotted lines that form no part of the claimed invention;
- FIG. 11 is a side elevation view as seen from left to right of the view shown in FIG. 2 with the boom and connection wiring shown in dotted lines that form no part of the claimed invention;
- FIG. 12 is a side elevation view as seen from right to left of the view shown in FIG. 2 with the boom and connection wiring shown in dotted lines that form no part of the claimed invention;
- FIG. 13 is a top plan view thereof with the boom and connection wiring shown in dotted lines that form no part of the claimed invention; and,
- FIG. 14 is a bottom plan view thereof with the boom and connection wiring shown in dotted lines that form no part of the claimed invention.

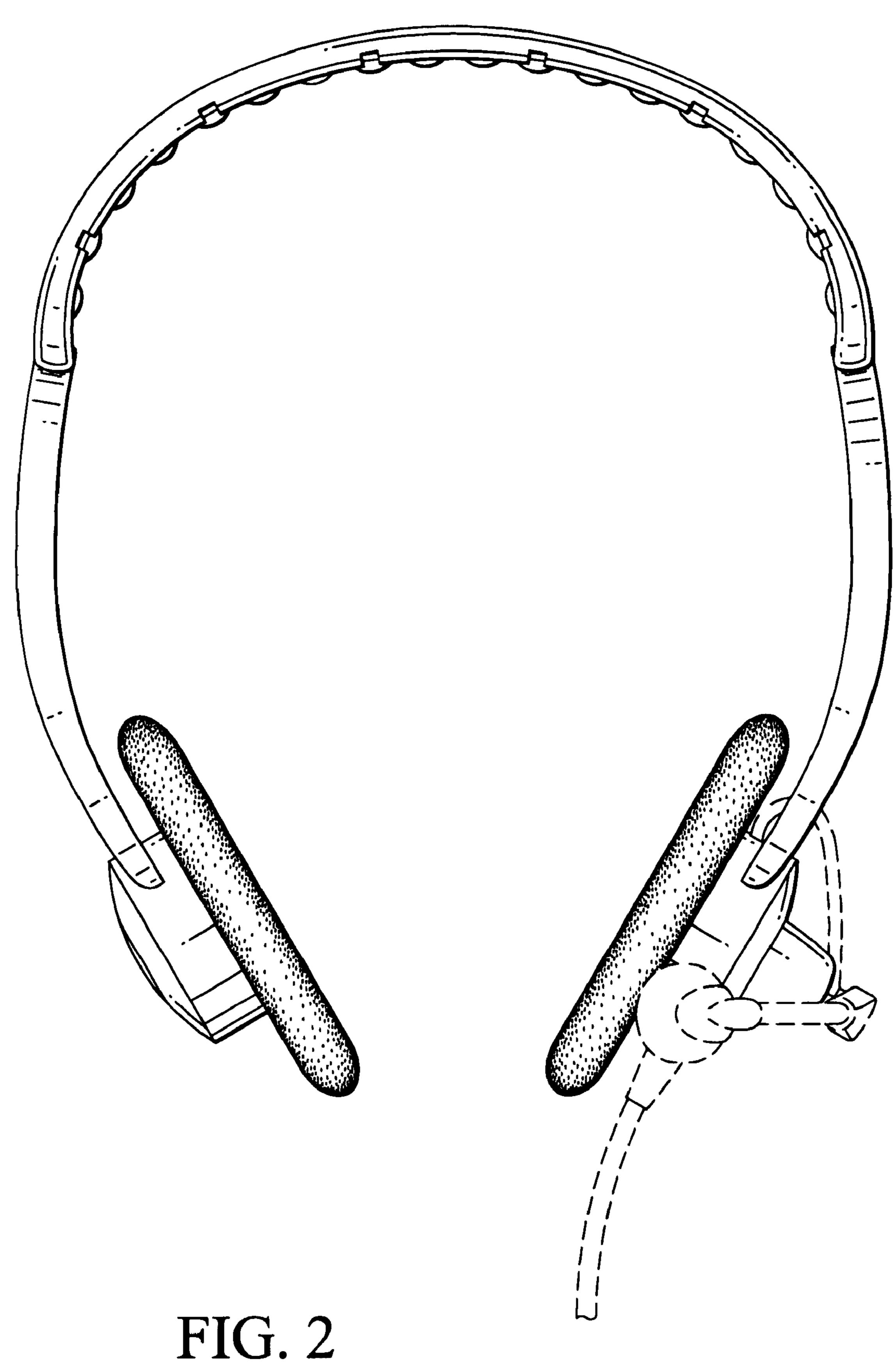
1 Claim, 14 Drawing Sheets

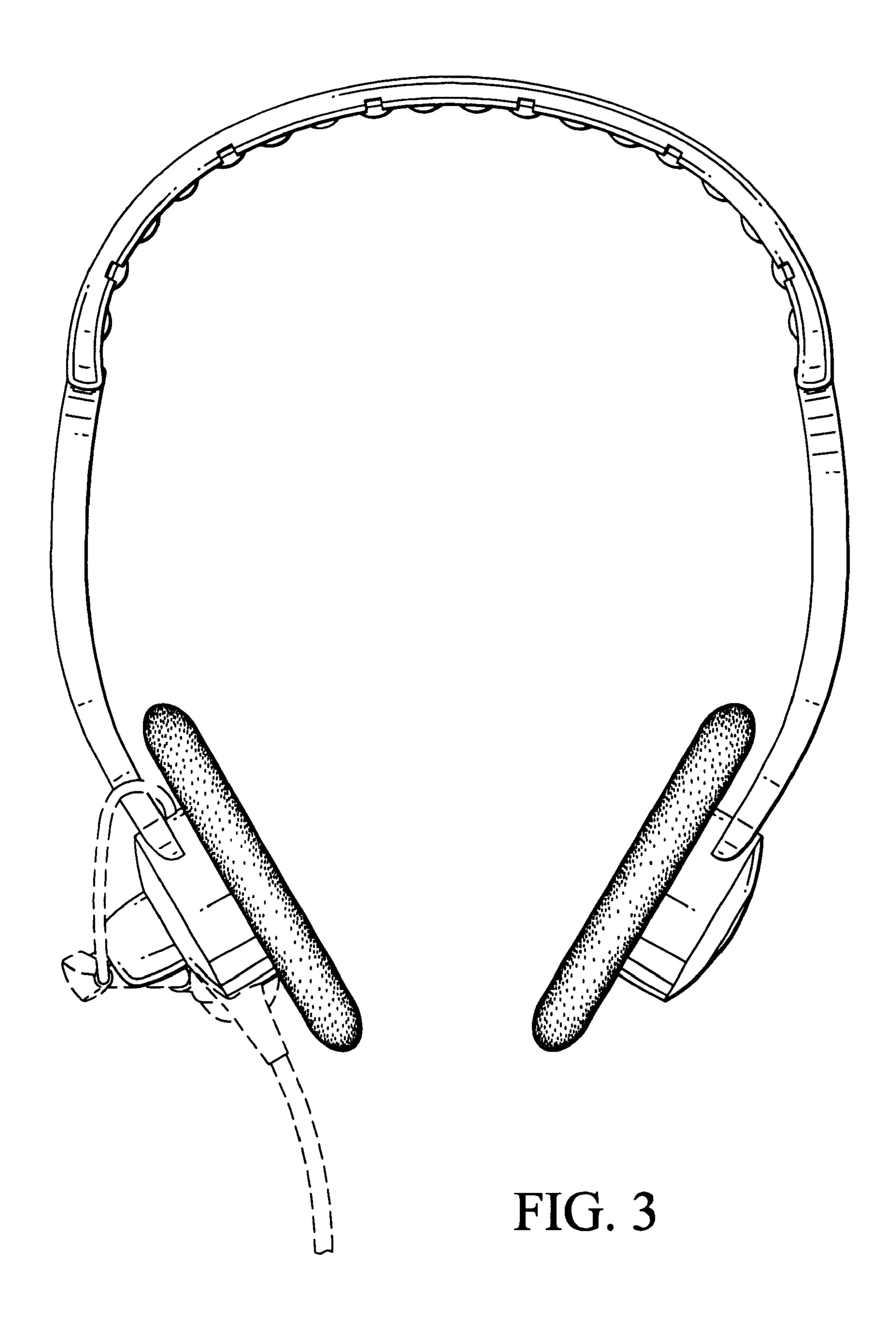


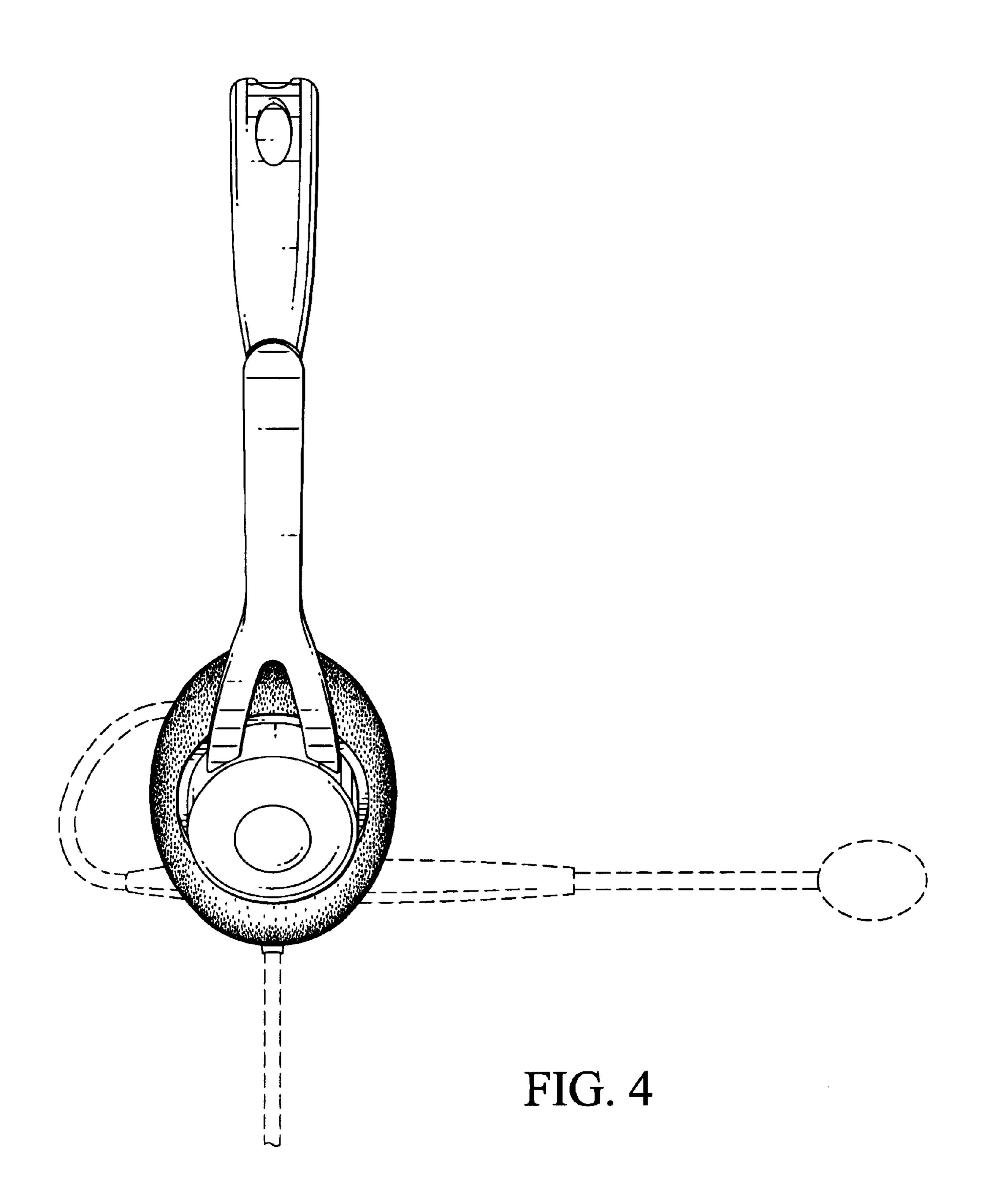
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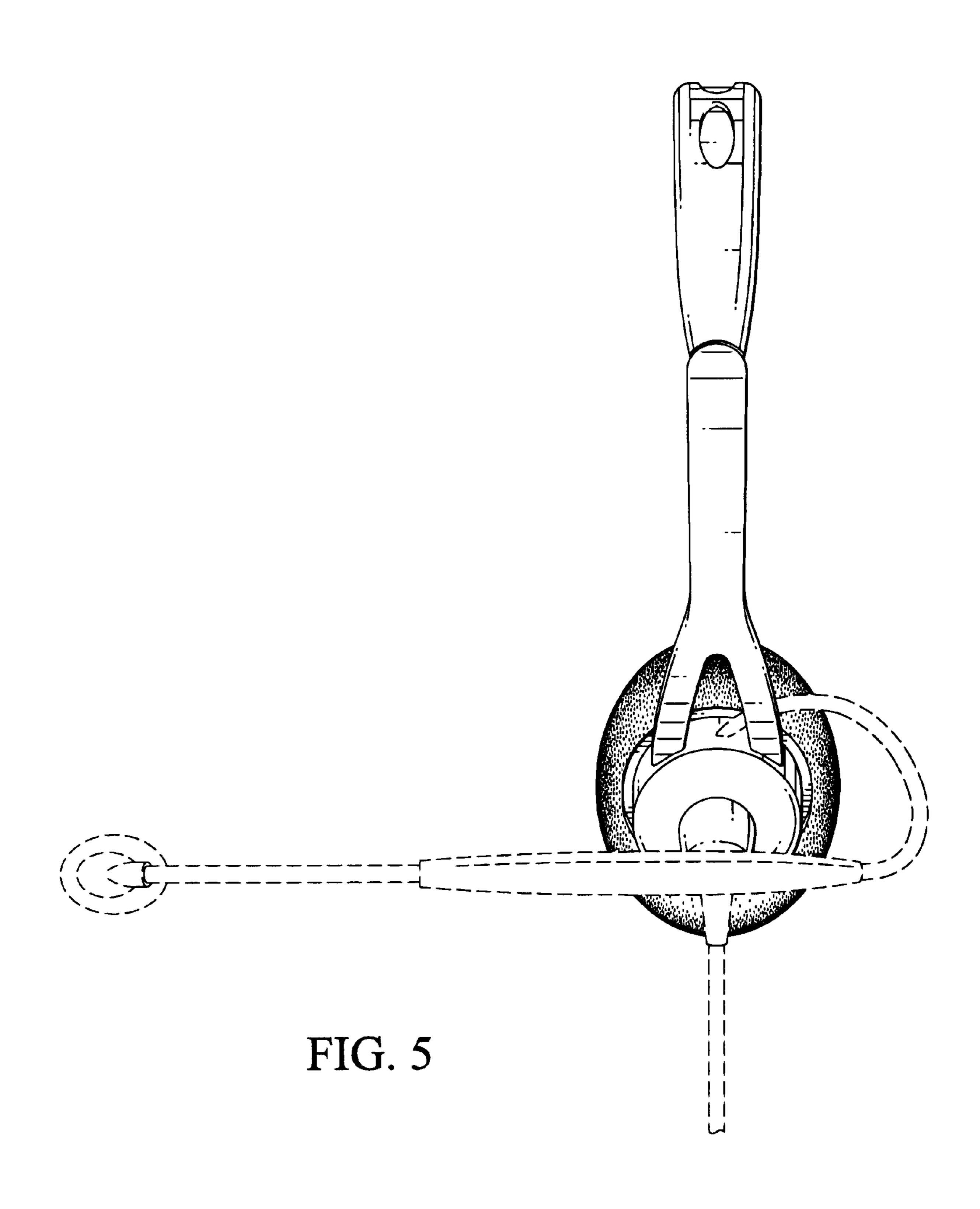
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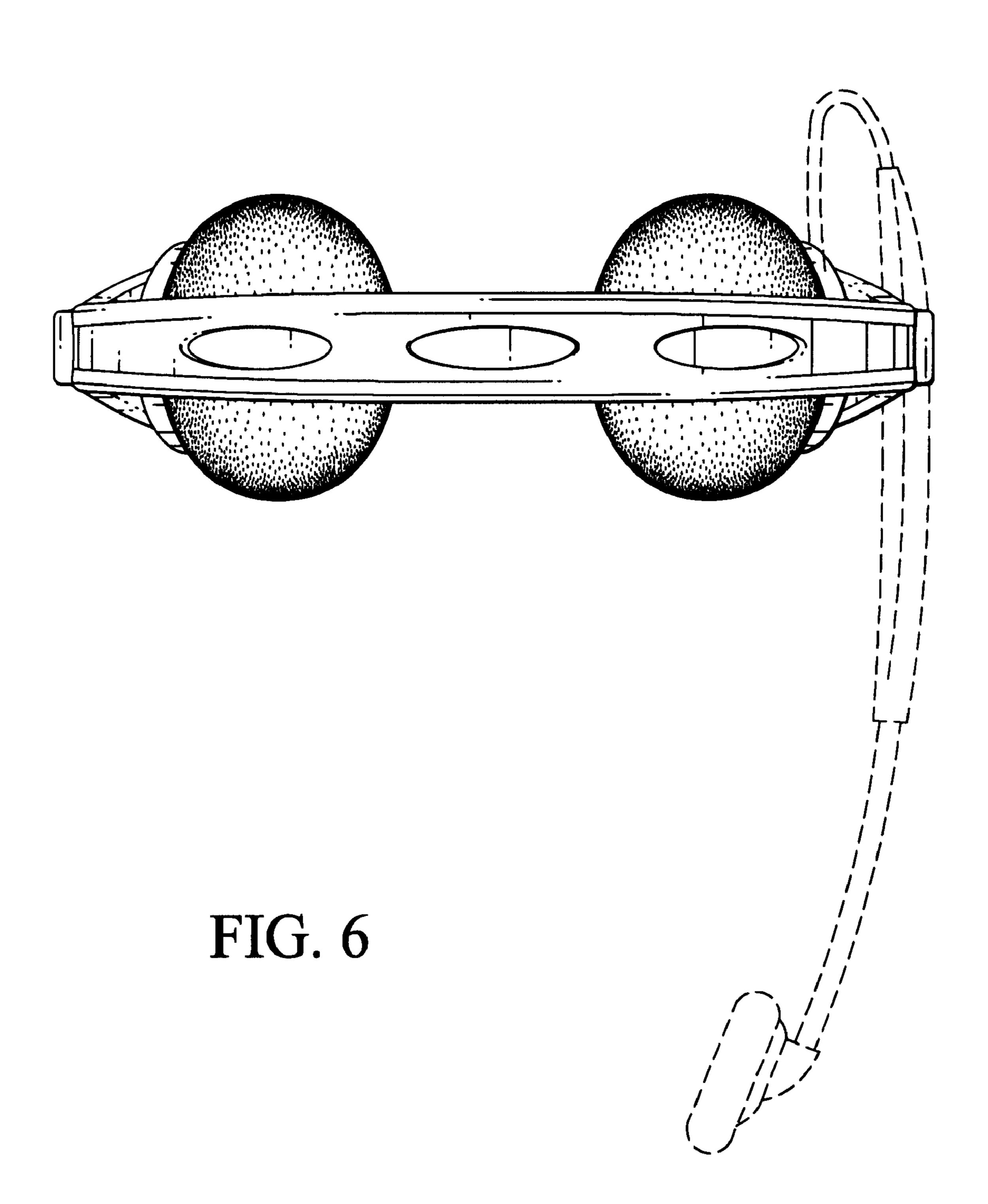












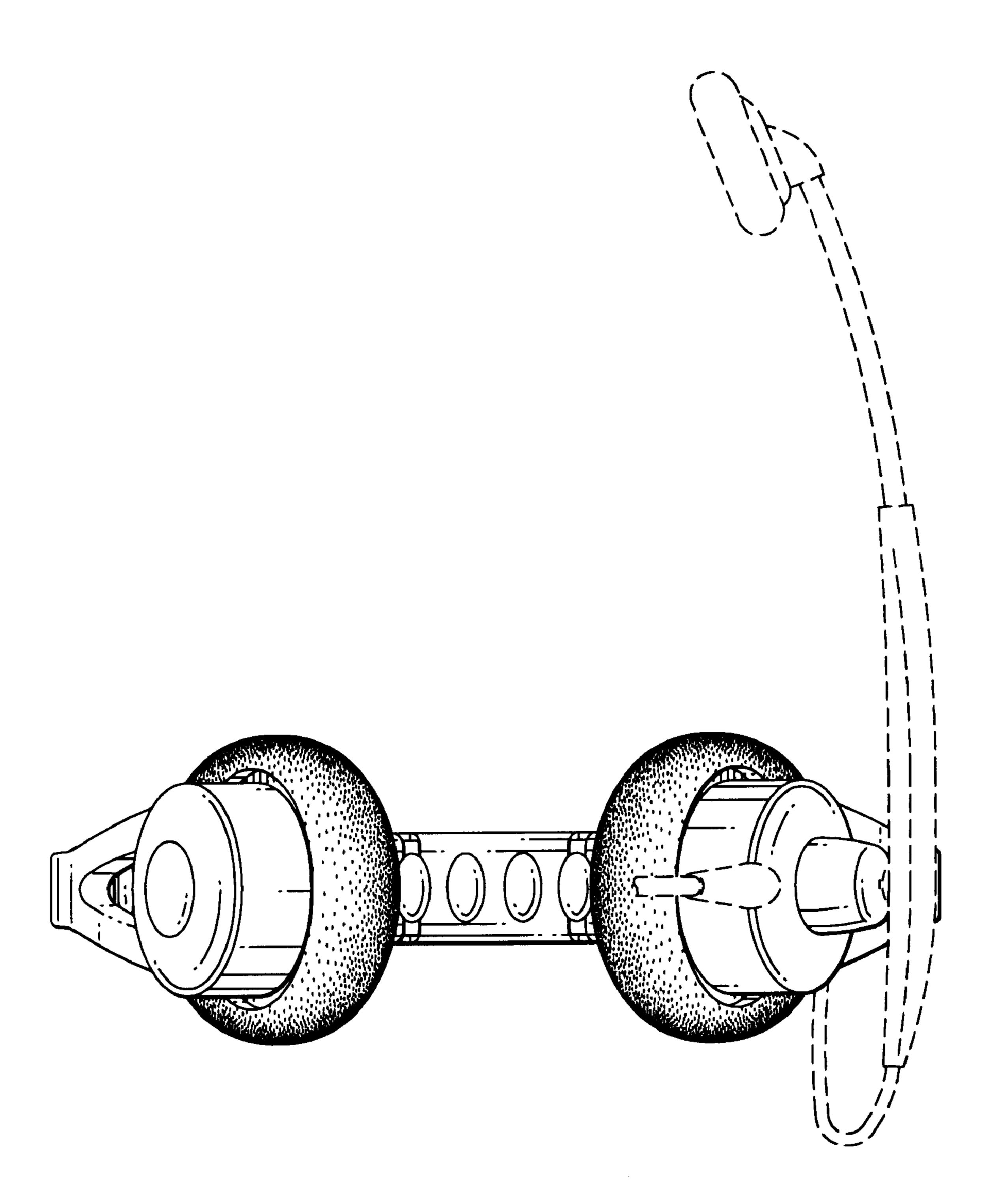
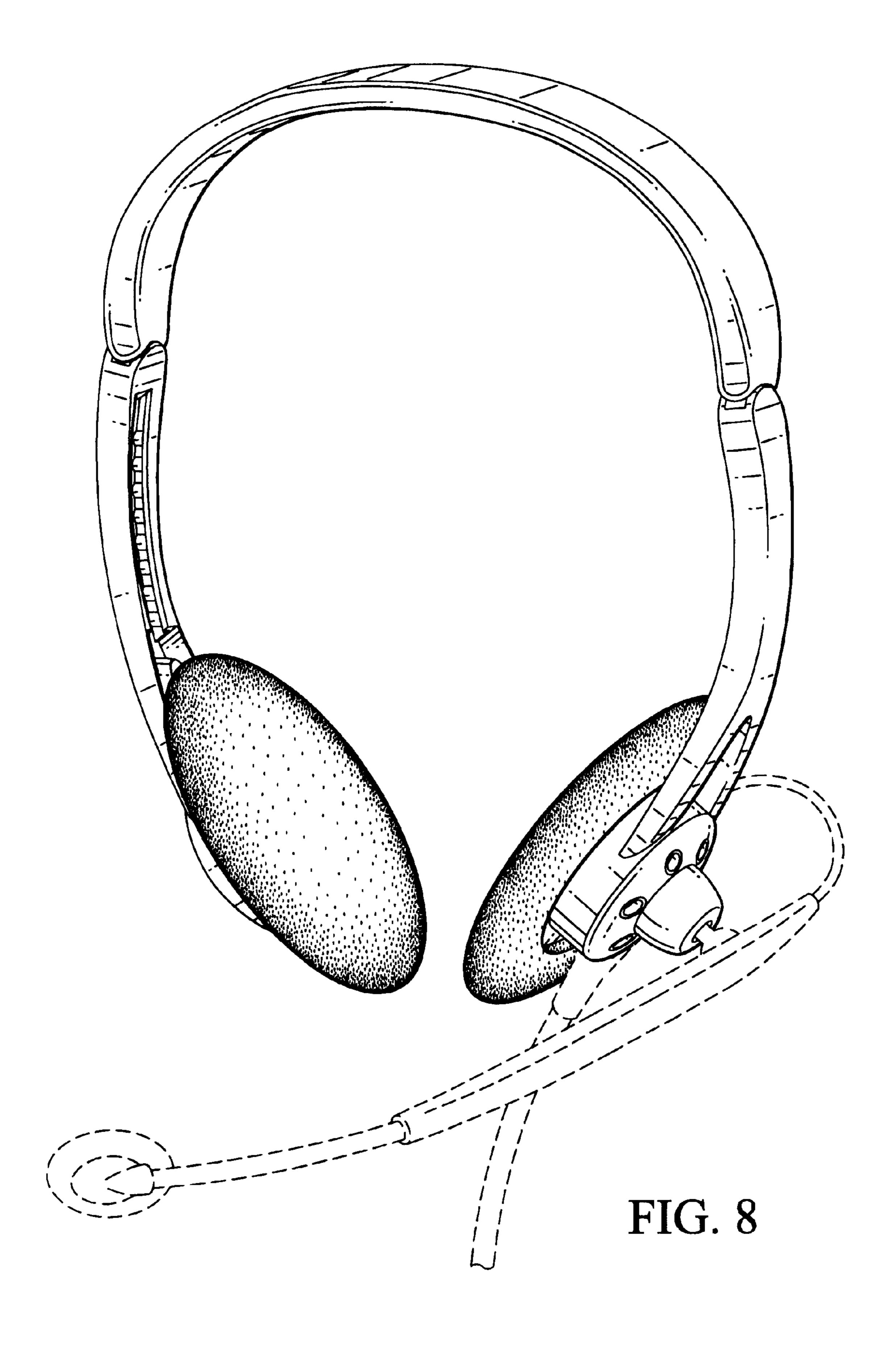
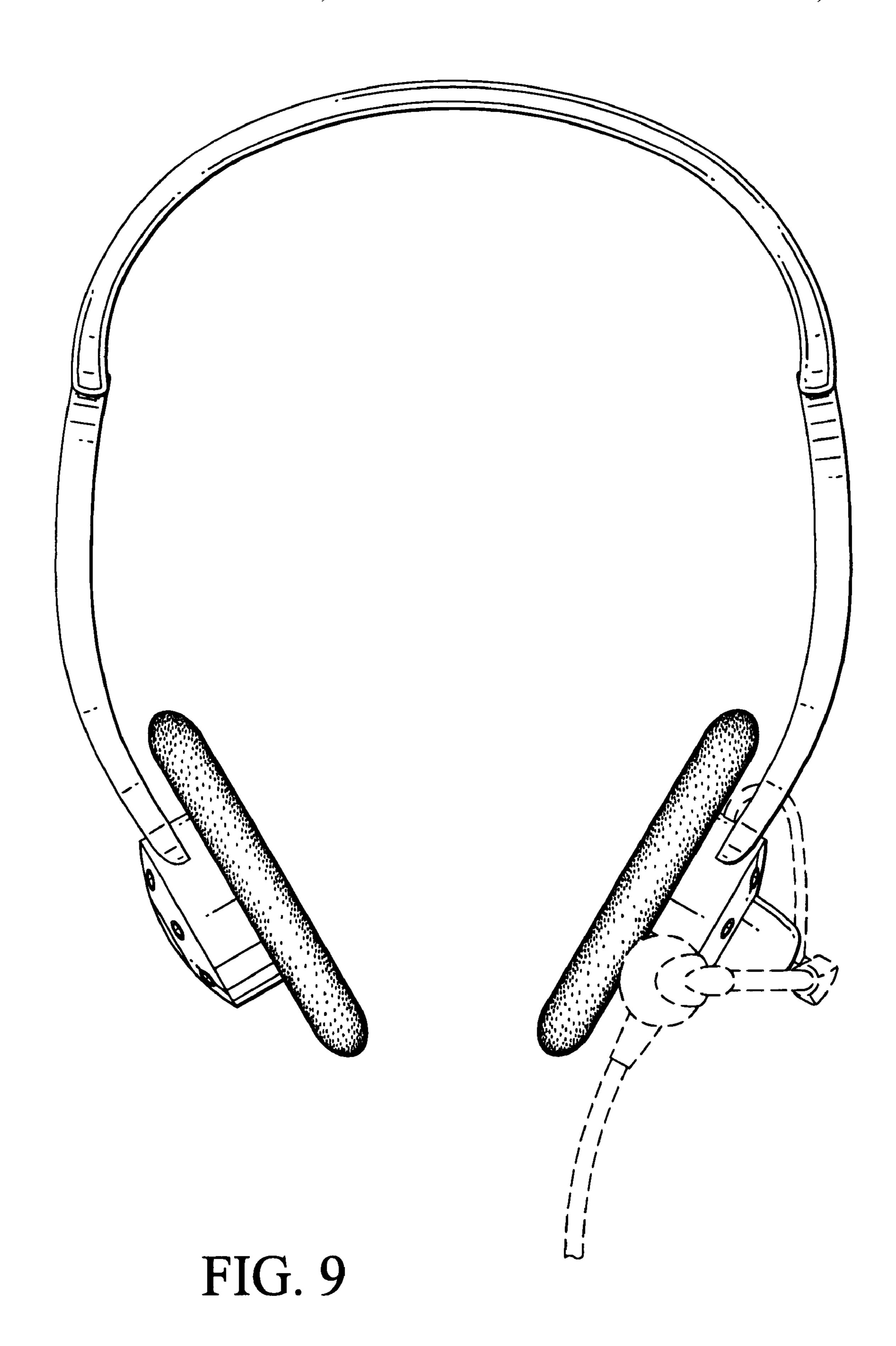
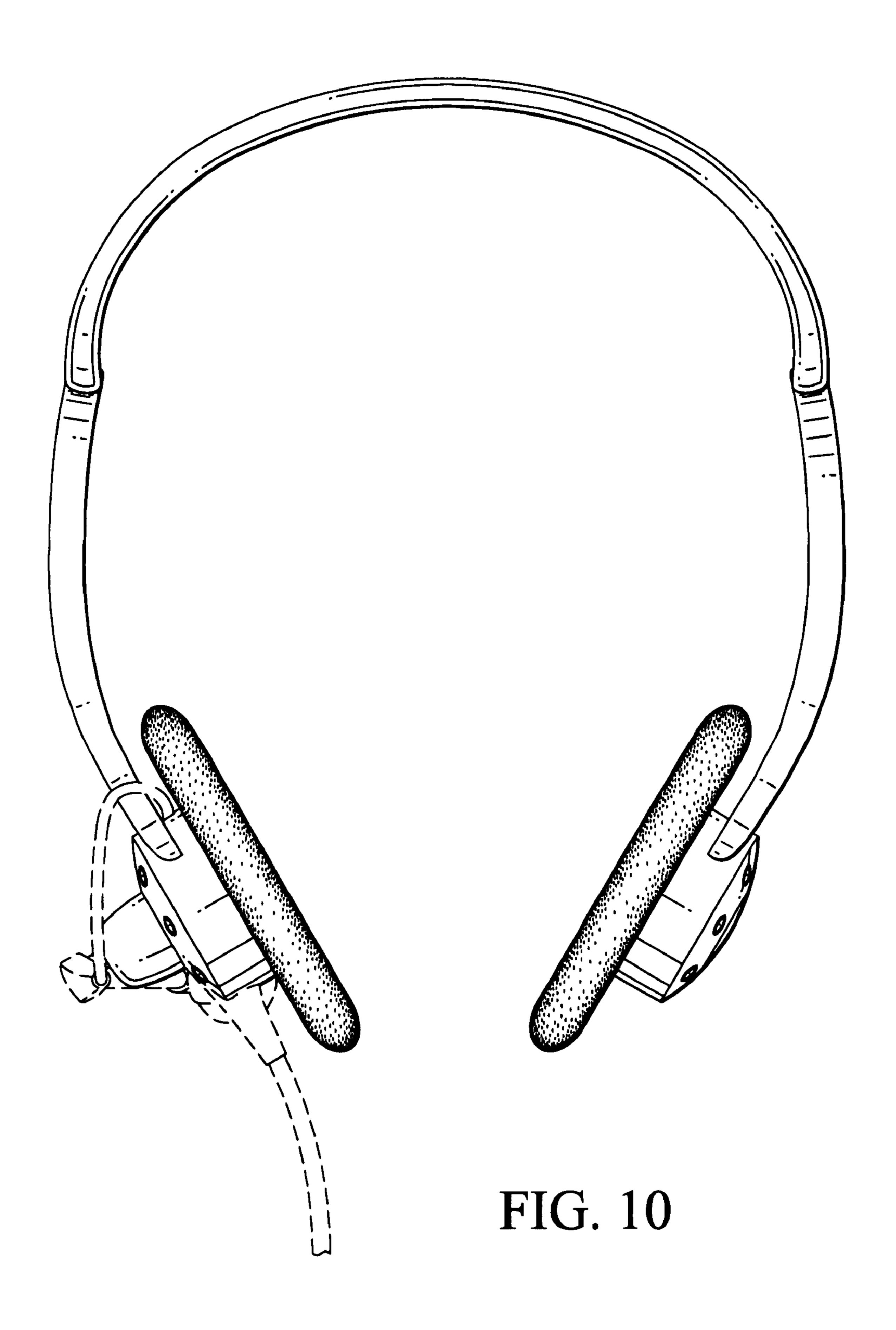
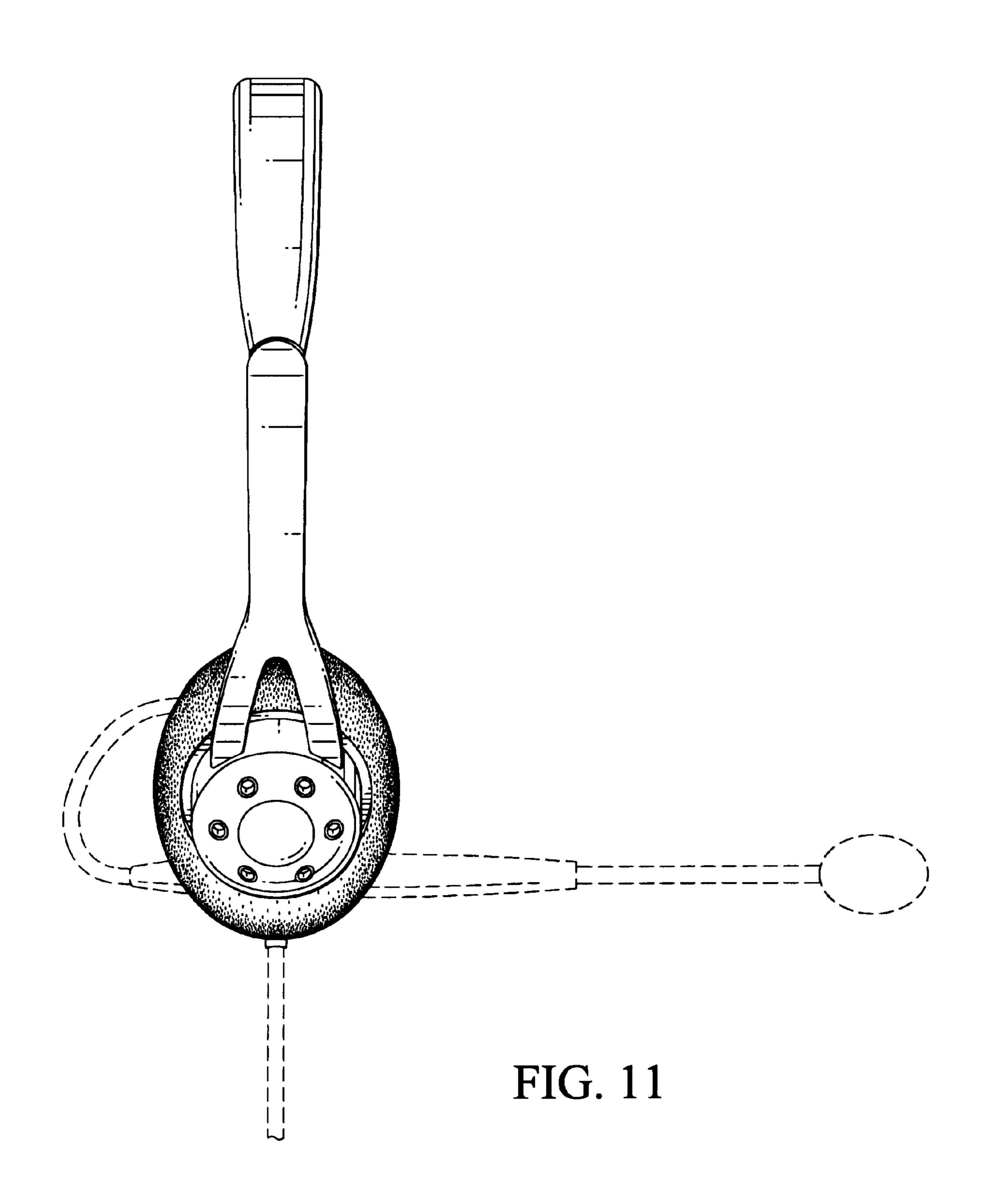


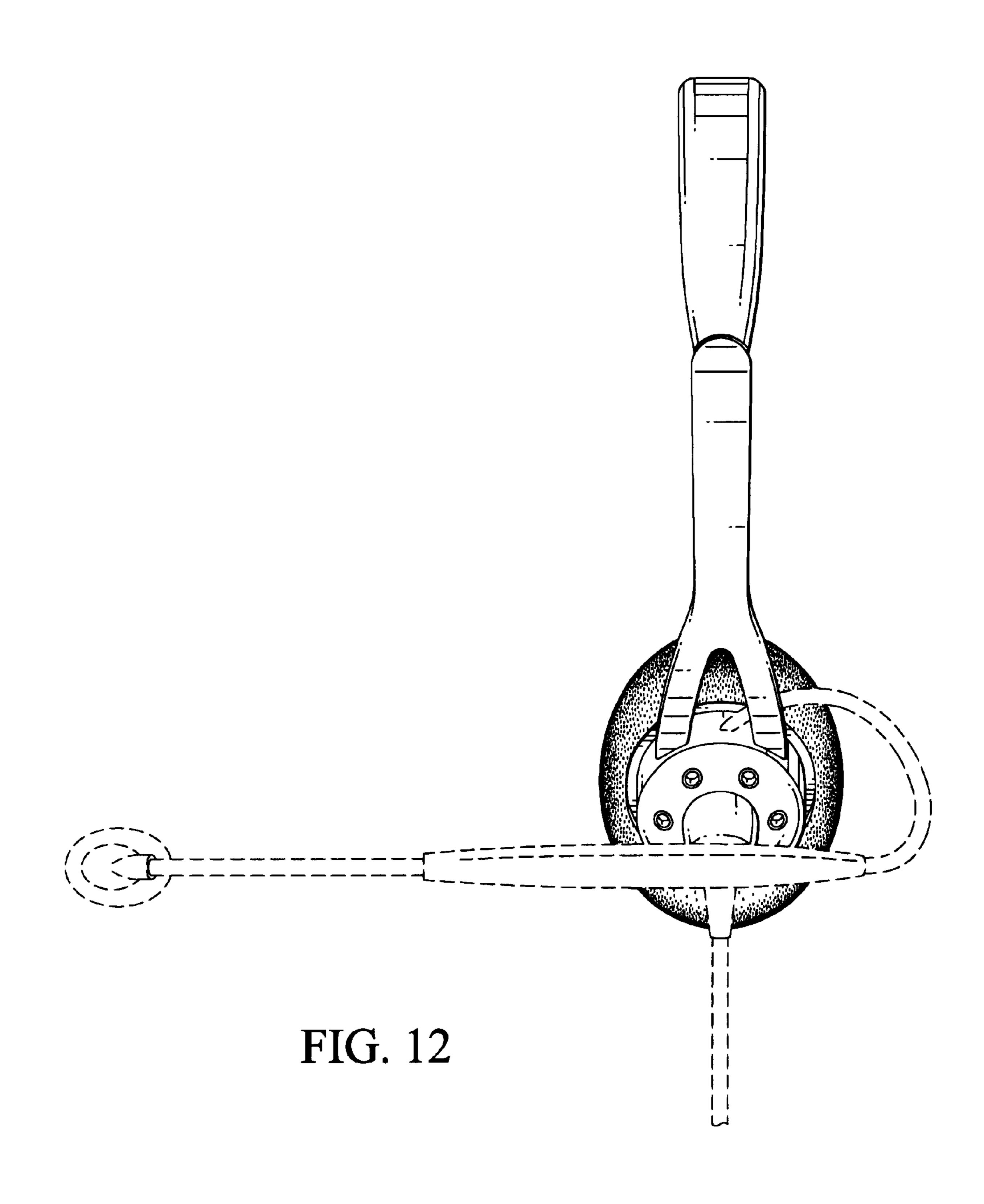
FIG. 7

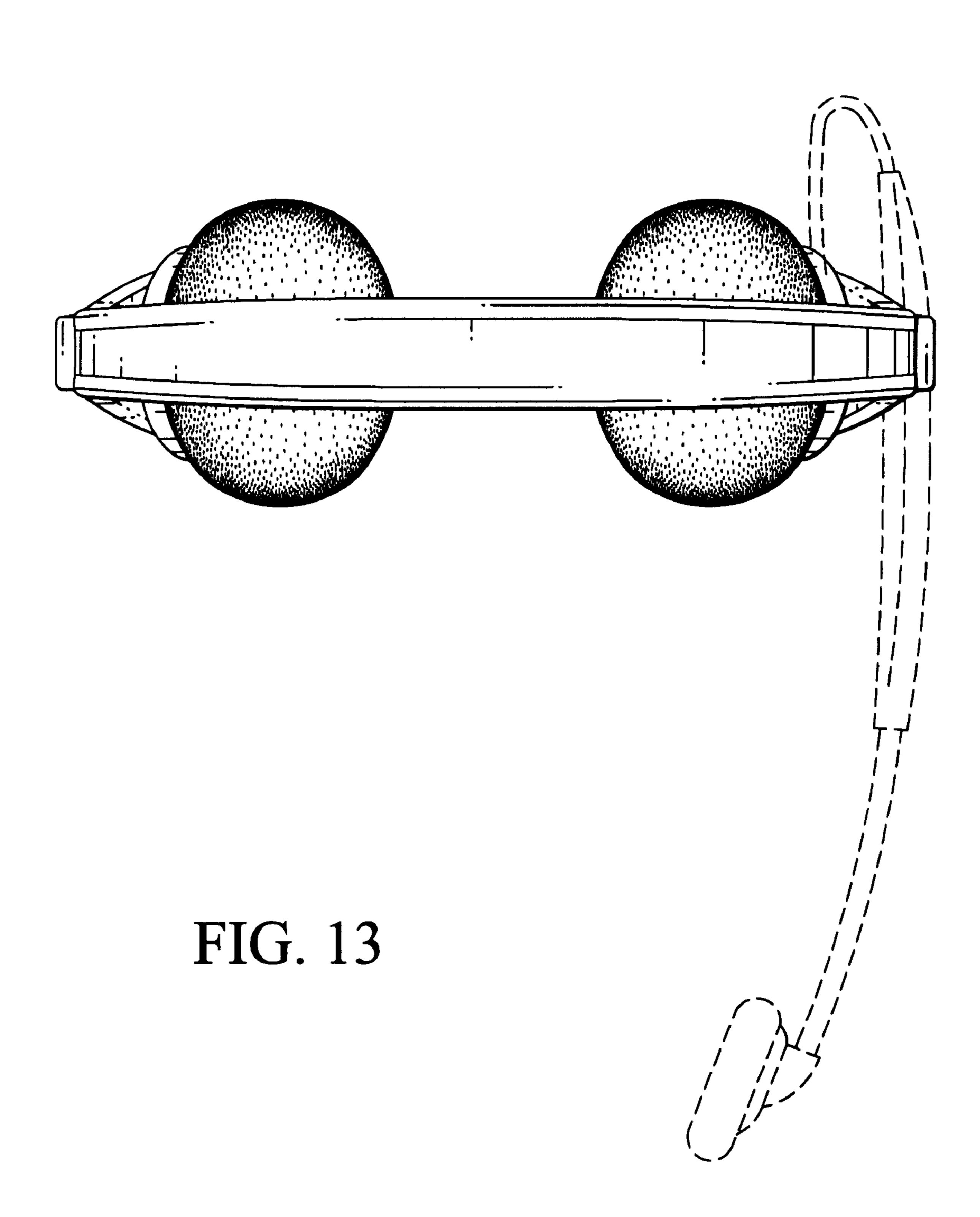












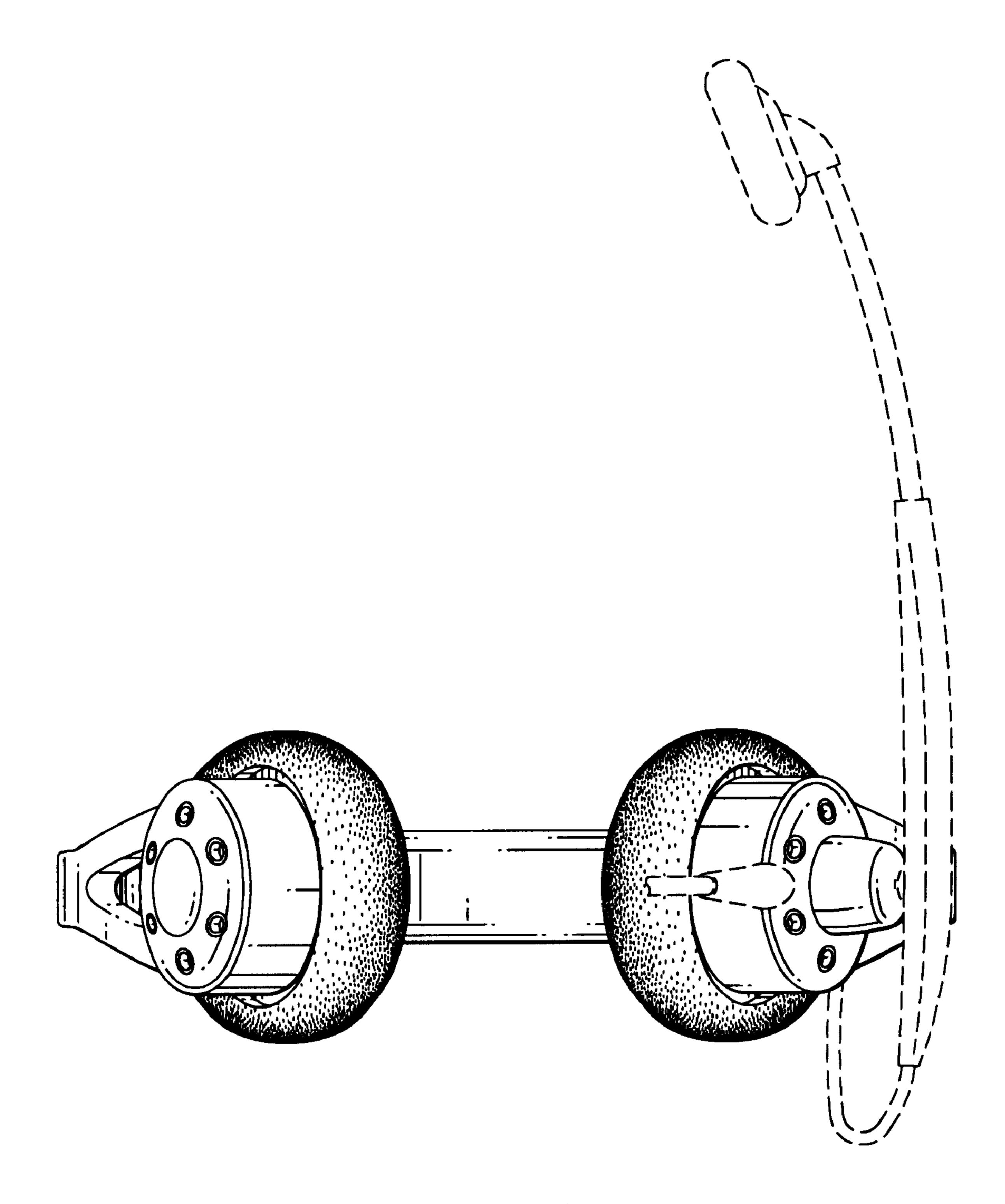


FIG. 14